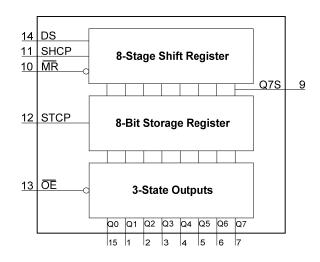


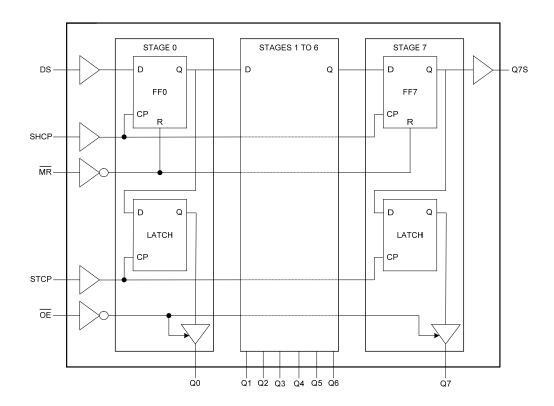
Pin Descriptions

Pin Number	Pin Name	Description
1	Q1	Parallel Data Output 1
2	Q2	Parallel Data Output 2
3	Q3	Parallel Data Output 3
4	Q4	Parallel Data Output 4
5	Q5	Parallel Data Output 5
6	Q6	Parallel Data Output 6
7	Q7	Parallel Data Output 7
8	GND	Ground
9	Q7S	Serial Data Output
10	MR	Master Reset Input
11	SHCP	Shift Register Clock Input
12	STCP	Storage Register Clock Input
13	ŌE	Output Enable Input
14	DS	Serial Data Input
15	Q0	Parallel Data Output 0
16	Vcc	Supply Voltage

Functional Diagram



Logic Diagram

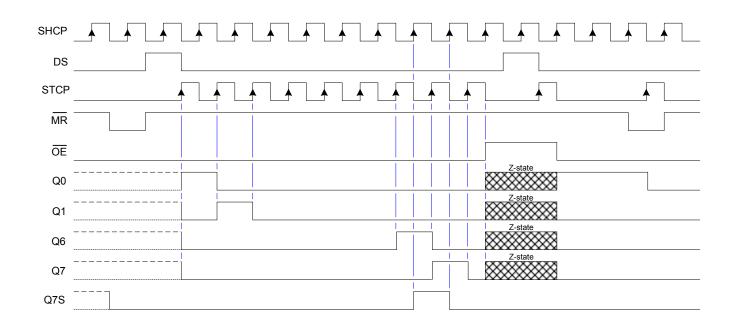




Functional Description and Timing Diagram

	Contr	rol		Input	Output		Firmation
SHCP	STCP	OE	MR	DS	Q7S	Qn	Function
Х	Х	L	L	-	L	NC	Low-level asserted on MR clears shift register. Storage register is unchanged
Х	↑	L	L	_	L	L	Empty shift register transferred to storage register
Х	Х	Н	L	_	L	Z	Shift register remains clear;: All Q ouputs in Z state.
↑	x	L	Н	_	Q6S	NC	HIGH is shifted into first stage of Shift Register Contents of each register shifted to next register The content of Q6S has been shifted to Q7S and now appears on device pin Q7S
Х	1	L	Н	-	NC	QnS	Contents of shift register copied to storage register. With output now in active state the storage resister contents appear on Q outputs.
↑	↑	L	Н	-	Q6S	QnS	

H=HIGH voltage state L=LOW voltage state ↑=LOW to HIGH transition X= don't care – high or low (not floating) NC= No change Z= high-impedance state





Absolute Maximum Ratings (Note 4) (@T_A = +25°C, unless otherwise specified.)

Symbol	Parameter	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	KV
ESD CDM	Charged Device Model ESD Protection	1	KV
ESD MM	Machine Model ESD Protection	200	V
Vcc	Supply Voltage Range	-0.5 to 7.0	V
VI	Input Voltage Range	-0.5 to 7.0	V
Vo	Voltage applied to output in high or low state	-0.3 to V _{CC} +0.5	V
I _{IK}	Input Clamp Current V _I < -0.5V	-20	mA
I _{OK}	Output Clamp Current V _O <-0.5V	-20	mA
I _{OK}	Output Clamp Current V _O > V _{CC} + 0.5V	25	mA
I _O	Continuous output current	+/- 25	mA
Icc	Continuous current through Vcc or GND	75	mA
I _{GND}	Continuous current through Vcc or GND	-75	mA
TJ	Operating Junction Temperature	-40 to 150	°C
T _{STG}	Storage Temperature	-65 to 150	°C
Ртот	Total Power Dissipation	500	mW

Note:

Recommended Operating Conditions (Note 5) (@TA = +25°C, unless otherwise specified.)

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CC}	Supply Voltage	-	2.0	5.5	V
Vı	Input Voltage	-	0	5.5	V
Vo	Output Voltage	Active Mode	0	V _{CC}	V
Δt/ΔV	Input transition Rise or Fall Rate	V _{CC} = 3.0V to 3.6V	-	100	ns/V
ΔυΔν	Imput transition Rise of Fall Rate	V _{CC} = 4.5V to 5.5V	=	20	115/ V
T _A	Operating Free-Air Temperature	-	-40	+125	°C

Note:

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Symbol	Parameter	Test Conditions	Vcc	Т	_A = +25°	,C	$T_A = -40^{\circ}$	C to +85°C	$T_A = -40^{\circ}C$	to +125°C	Unit
Symbol	i arameter	rest conditions	VCC	Min	Тур	Max	Min	Max	Min	Max	Oilit
	Link lavel land	=	2.0V	1.5	_	-	1.5	-	1.5	-	
V_{IH}	High-level Input Voltage	=	3.0V	2.1	_	-	2.1	-	2.1	-	V
	Voltage	=	5.5V	3.85	_	-	3.85	-	3.85	-	
	l avv laval innut	=	2.0V	-	_	0.5	-	0.5	-	0.5	
V_{IL}	Low-level input voltage	=	3.0V	-	_	0.9	-	0.9	-	0.9	V
	voltage	_	5.5V	-	-	1.65	_	1.65	-	1.65	
		I _{OH} = -50μA	2.0V	1.9	2.0	-	1.9	-	1.9	-	
	l	I _{OH} = -50μA	3.0V	2.9	3.0	_	2.9	_	2.9	_	
VoH	High Level Output Voltage	I _{OH} = -50μA	4.5V	4.4	4.5	-	4.4	-	4.4	-	٧
	Output Voltage	I _{OH} = -4mA	3.0V	2.58	_	_	2.48	_	2.40	_	
		I _{OH} = -8mA	4.5V	3.94	_	-	3.80	-	3.70	=	1
		I _{OL} = 50μA	2.0V	-	0	0.1	-	0.1	-	0.1	
	l	I _{OL} = 50μA	3.0V	-	0	0.1	_	0.1	-	0.1	
V_{OL}	Low-level Output Voltage	I _{OL} = 50μA	4.5V	-	0	0.1	_	0.1	-	0.1	V
	Output voltage	I _{OL} = 4mA	3.0V	-	_	0.36	-	0.44	-	0.55	
		I _{OL} = 8mA	4.5V	-	=	0.36	_	0.44	-	0.55	
lı	Input Current	V_I = GND to 5.5V	5.5V	-	0.1	±0.1	_	±1	-	±2	μΑ
l _{OZ}	OFF-state	$V_I = V_{IH} \text{ or } V_{IL};$	5.5V		_	±0.25	_	±2.5		±10	μA
102	OZ output current	$V_O = V_{CC}$ or GND	$V_O = V_{CC}$ or GND	_	10.23	_	12.5	_	110	μΛ	
Icc	Supply Current	$V_I = GND \text{ or } V_{CC} I_O = 0$	5.5V	_	=	4.0	=	40	-	80	μA
Ci	Input Capacitance	V _i = V _{CC} or GND	5.5V	_	4	10	=	10	-	10	pF

^{4.} Stresses beyond the absolute maximum may result in immediate failure or reduced reliability. These are stress values and device operation should be within recommend values.

^{5.} Unused inputs should be held at V_{CC} or Ground.



Switching Characteristics

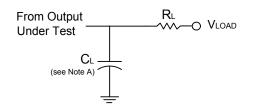
Symbol /	Pins	Test Conditions	V	Т	A = +25°	С	-40°C to	o +85°C	-40°C to	+125°C	Unit									
Parameter	Pins	lest Conditions	V _{CC}	Min	Тур	Max	Min	Max	Min	Max	Unit									
f _{MAX}			3.0V to 3.6V	80	125	_	60	_	40	_										
Maximum Frequency	SHCP or STCP	Figure 2	4.5V to 5.5V	130	70	-	110	-	90	-	MHz									
	SHCP	Figure 2	3.0V to 3.6V	5.0	_	_	5.0	_	5.0	_										
	HIGH or LOW	Figure 2	4.5V to 5.5V	5.0	_	-	5.0	_	5.0	-										
t _W	STCP	Figure 2	3.0V to 3.6V	5.0	_	-	5.0	_	5.0	-	ns									
Pulse Width	HIGH or LOW	rigure 2	4.5V to 5.5V	5.0	_	-	5.0	_	5.0	-	115									
	MD LOW	Figure 2	3.0V to 3.6V	5.0	_	_	5.0	_	5.0	_										
	MR LOW	Figure 2	4.5V to 5.5V	5.0	_	_	5.0	_	5.0	_										
	DS to SHCP	Fig 0	3.0V to 3.6V	3.5	_	_	3.5	=	3.5	-										
tsu	DS 10 SHCP	Figure 2	4.5V to 5.5V	3.0	_	_	3.0	=	3.0	-	ns									
Set-up Time	OLIOD to OTOD	Fig 0	3.0V to 3.6V	8.5	_	-	8.5	-	8.5	-										
	SHCP to STCP	Figure 2	4.5V to 5.5V	5.0	_	_	5.0	_	5.0	_	ns									
t _H	DO 4- 0110D	Fig 0	3.0V to 3.6V	1.5	=	=	1.5	=	1.5	-										
Hold Time	DS to SHCP	Figure 2	4.5V to 5.5V	2.0	_	=	2.0	=	2.0	=	ns									
t _{REC}	MR to SHCP		MD to OUIOD					Fig 0	3.0V to 3.6V	3.0	_	=	3.0	=	3.0	=				
Recovery Time			Figure 2	4.5V to 5.5V	2.5	_	=	2.5	=	2.5	=	ns								
		Figure 2	3.0V to 3.6V	_	5.7	13.0	1.0	15.0	1.0	16.5										
	SHCP to Q7S	$C_L = 15pF$	4.5V to 5.5V	_	4.0	8.2	1.0	9.4	1.0	10.5										
	SHCP 10 Q/S	SHCP 10 Q/S	3HCF 10 Q/3	3HCF 10 Q/3	3HCF 10 Q/3	3HCF 10 Q/3	SHCP 10 Q/S	SHCP 10 Q/S	3HCP 10 Q/3	SHCP to Q75	Figure 2	3.0V to 3.6V	_	7.7	16.5	1.0	18.5	1.0	20.1	ns
		$C_L = 50pF$	4.5V to 5.5V	_	5.4	10.0	1.0	11.4	1.0	12.5										
		Figure 2	3.0V to 3.6V	_	5.9	11.9	1.0	13.5	1.0	15.0										
t _{PD}	STCP to Qn	$C_L = 15pF$	4.5V to 5.5V	_	4.2	7.4	1.0	8.5	1.0	10.5										
Propagation Delay	31CP 10 Q11	Figure 2	3.0V to 3.6V	_	7.7	15.4	1.0	17.0	1.0	18.5	ns									
Delay		$C_L = 50pF$	4.5V to 5.5V	_	5.5	9.0	1.0	10.5	1.0	11.5										
		Figure 2	3.0V to 3.6V	_	5.9	12.8	1.0	13.7	1.0	15.0										
		$C_L = 15pF$	4.5 V to 5.5V	=	4.4	8.0	1.0	9.1	1.0	10.5										
	MR to Q7S	Figure 2	3.0V to 3.6V	_	7.4	16.3	1.0	17.2	1.0	18.7	ns									
		$C_L = 50pF$	4.5V to 5.5V	-	5.6	10.0	1.0	11.1	1.0	12.0										
		Figure 2	3.0V to 3.6V	=	5.6	11.5	1.0	13.5	1.0	15.0										
t _{EN}		C _L = 15pF	4.5V to 5.5V	_	4.0	8.6	1.0	10.0	1.0	10.5										
Enable Time	OE to Qn	Figure 2	3.0V to 3.6V	_	7.4	15.0	1.0	17.0	1.0	18.5	ns									
		C _L = 50pF	4.5V to 5.5V	-	5.3	10.6	1.0	12.0	1.0	13.0	1									
		Figure 2	3.0V to 3.6V	-	5.4	11.0	1.0	13.0	1.0	14.5										
t _{DIS}		C _L = 15pF	4.5V to 5.5V	-	3.8	8.0	1.0	9.5	1.0	10.5	_									
Disable Time	OE to Qn	Figure 2	3.0V to 3.6V	-	8.7	15.7	1.0	16.2	1.0	17.5	ns									
		C _L = 50pF	4.5V to 5.5V	-	5.8	10.3	1.0	11.0	1.0	12.0										

Operating Characteristics (@T_A = +25°C, unless otherwise specified.)

	Parameter	Test Conditions	V _{CC} = 5V Typ	Unit
$C_{\sf pd}$	Power dissipation capacitance	f = 1 MHz all outputs switching-no load	42	pF

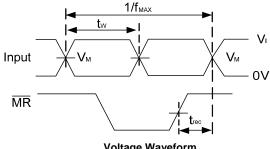


Parameter Measurement Information

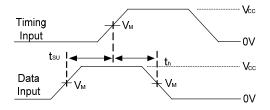


TEST	Vload
t _{PLH} /t _{PHL}	Open
t _{PLZ} /t _{PZL}	Vcc
t _{PHZ} /t _{PZH}	GND

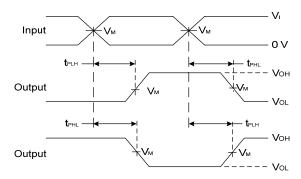
Voc	Inp	outs	V	C.	
Vcc	VI	t _r /t _f	V _M	CL	
3.3V -3.6V	Vcc	3ns	V _{CC} /2	15pF, 50pF	
4.5V to 5.5V	V _{CC}	3ns	V _{CC} /2	15pF, 50pF	



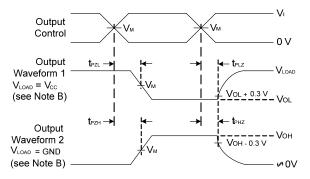
Voltage Waveform Pulse Duration and Recovery Time



Voltage Waveform Set-up and Hold Times



Voltage Waveform
Propagation Delay Times
Inverting and Non Inverting Outputs



Voltage Waveform Enable and Disable Times

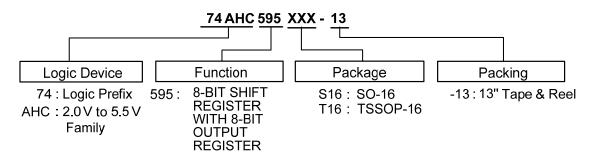
Notes: A .Includes test lead and test apparatus capacitance.

- B. Output Waveform 1 depends on the internal Q_N node being low and behaves in this manner based on OE pin. Output Waveform 2 depends on the internal Q_N node being high and behaves in this manner based on OE pin.
- C. All pulses are supplied at pulse repetition rate ≤ 10 MHz
- D. Inputs are measured separately one transition per measurement
- E. t_{PLH} and t_{PHL} are the same as $t_{\text{PD.}}$

Figure 2. Load Circuit and Voltage Waveforms



Ordering Information

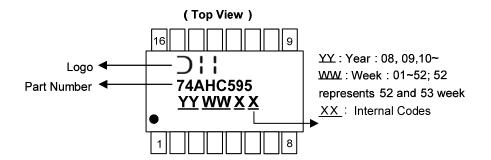


Part Number	Package Code Packaging —		7" Tape and	Reel (Note 6)
Part Number	Fackage Code	rackaging	Quantity	Part Number Suffix
74AHC595S16-13	S16	SO-16	2500/Tape & Reel	-13
74AHC595T16-13	T16	TSSOP-16	2500/Tape & Reel	-13

Note: 6. The taping orientation is located on our website at http://www.diodes.com/datasheets/ap02007.pdf

Marking Information

(1) SO-16, TSSOP16



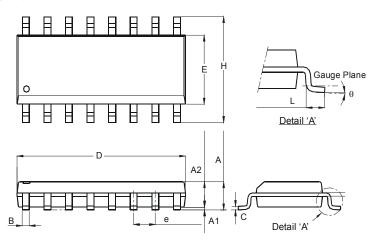
Part Number	Package		
74AHC595S16	SO-16		
74AHC595T16	TSSOP-16		



Package Outline Dimensions (All dimensions in mm.)

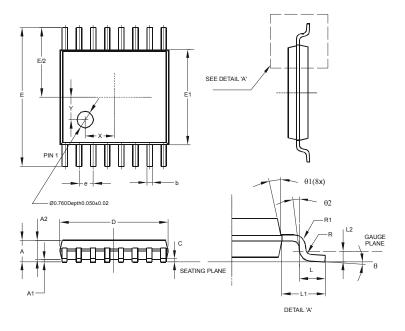
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.

Package Type: SO-16



	SO-16						
Dim	Min	Max					
Α	1.40	1.75					
A1	0.10	0.25					
A2	1.30	1.50					
В	0.33	0.51					
С	0.19	0.25					
D	9.80	10.00					
Е	3.80	4.00					
е	1.27	Тур					
Н	5.80	6.20					
L	0.38	1.27					
Θ	0°	8°					
All Dimensions in mm							

Package Type: TSSOP-16



TSSOP-16				
Dim	Min	Max	Тур	
Α	-	1.08	-	
A1	0.05	0.15	-	
A2	0.80	0.93	-	
b	0.19	0.30	-	
C	0.09	0.20	1	
D	4.90	5.10	1	
Е	6.40 BSC			
E1	4.30	4.50	-	
е	0.65 BSC			
L	0.45	0.75	-	
L1	1.00 REF			
L2	0.25 BSC			
R	0.09	ı	1	
R1	0.09	ı	ı	
X	-	ı	1.350	
Υ	-	ı	1.050	
Θ	0°	8°	ı	
Θ1	5°	15°	-	
Θ2	0°	-	-	
All Dimensions in mm				

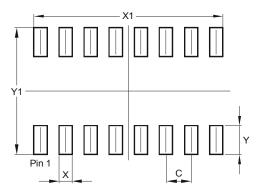
Downloaded from **Arrow.com**.



Suggested Pad Layout

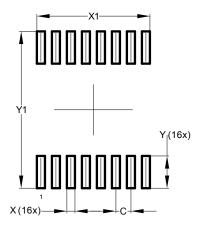
Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.

Package Type: SO-16



Dimensions	Value (in mm)	
С	1.270	
Х	0.670	
X1	9.560	
Y	1.450	
Y1	6.400	

Package Type: TSSOP-16



Dimensions	Value (in mm)	
С	0.650	
Х	0.350	
X1	4.900	
Y	1.400	
Y1	6 800	



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